

200 mA LOAD SWITCH FEATURING PRE-BIASED PNP TRANSISTOR AND N-MOSFET WITH GATE PULL DOWN RESISTOR

General Description

LMN200B02 is best suited for applications where the load needs to be turned on and off using control circuits like micro-controllers, comparators etc. particularly at a point of load. It features a discrete pass transistor with stable $V_{CE(SAT)}$ which does not depend on the input voltage and can support continuous maximum current of 200 mA. It also contains a discrete N-MOSFET that can be used as control. This N-MOSFET also has a built-in pull down resistor at its gate. The component can be used as a part of a circuit or as a stand alone discrete device.

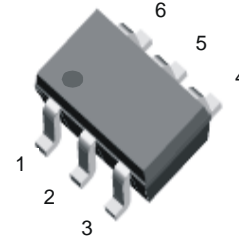


Fig. 1: SOT-363

Features

- Voltage Controlled Small Signal Switch
- N-MOSFET with Gate Pull-Down Resistor
- Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 8
- Ordering Information: See Page 8
- Weight: 0.006 grams (approximate)

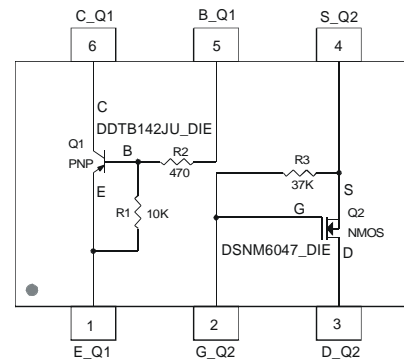


Fig. 2 Schematic and Pin Configuration

| Sub-Component P/N | Reference | Device Type | R1 (NOM) | R2 (NOM) | R3 (NOM) | Figure |
|---|-----------|----------------|----------|----------|----------|--------|
| DDTB142JU_DIE | Q1 | PNP Transistor | 10K | 470 | — | 2 |
| DSNM6047_DIE (with Gate Pull-Down Resistor) | Q2 | N-MOSFET | — | — | 37K | 2 |

Maximum Ratings, Total Device @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---|-----------|-------|----------------------|
| Power Dissipation (Note 3) | P_D | 200 | mW |
| Power Derating Factor above 125°C | P_{der} | 1.6 | mW/ $^\circ\text{C}$ |
| Output Current | I_{out} | 200 | mA |

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------------|---------------------------|
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |
| Thermal Resistance, Junction to Ambient Air (Equivalent to One Heated Junction of PNP Transistor) (Note 3) | $R_{\theta JA}$ | 625 | $^\circ\text{C}/\text{W}$ |

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

Maximum Ratings:

Sub-Component Device: Pre-Biased PNP Transistor (Q1)

@T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---------------------------|------------------|----------|------|
| Collector-Base Voltage | V _{CBO} | -50 | V |
| Collector-Emitter Voltage | V _{CEO} | -50 | V |
| Supply Voltage | V _{CC} | -50 | V |
| Input Voltage | V _{in} | +5 to -6 | V |
| Output Current | I _C | -200 | mA |

Sub-Component Device: N-MOSFET With Gate Pull-Down Resistor (Q2)

@T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---|------------------|--------------------------------------|------|
| Drain-Source Voltage | V _{DSS} | 60 | V |
| Drain Gate Voltage (R _{GS} ≤ 1M Ohm) | V _{DGR} | 60 | V |
| Gate-Source Voltage | V _{GSS} | Continuous | V |
| | | Pulsed (tp < 50 uS) | |
| Drain Current (Page 1: Note 3) | I _D | Continuous (V _{gs} = 10V) | 115 |
| | | Pulsed (tp < 10 uS, Duty Cycle < 1%) | 800 |
| Continuous Source Current | I _S | 115 | mA |

Electrical Characteristics: Pre-Biased PNP Transistor (Q1)

 @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|--------------------------------|-------|--------|-------|------|--|
| OFF CHARACTERISTICS | | | | | | |
| Collector-Base Cut Off Current | I _{CB0} | — | — | -100 | nA | V _{CB} = -50V, I _E = 0 |
| Collector-Emitter Cut Off Current | I _{CEO} | — | — | -500 | nA | V _{CE} = -50V, I _B = 0 |
| Emitter-Base Cut Off Current | I _{EBO} | — | -0.5 | -1 | mA | V _{EB} = -5V, I _C = 0 |
| Collector-Base Breakdown Voltage | V _{(BR)CBO} | -50 | — | — | V | I _C = -10 uA, I _E = 0 |
| Collector-Emitter Breakdown Voltage | V _{(BR)CEO} | -50 | — | — | V | I _C = -2 mA, I _B = 0 |
| Input Off Voltage | V _{I(OFF)} | — | -0.55 | -0.3 | V | V _{CE} = -5V, I _C = -100uA |
| Output Voltage | V _{OH} | -4.9 | — | — | V | V _{CC} = -5V, V _B = -0.05V, R _L = 1K |
| Output Current (leakage current same as I _{CEO}) | I _{O(OFF)} | — | — | -500 | nA | V _{CC} = -50V, V _I = 0V |
| ON CHARACTERISTICS | | | | | | |
| Collector-Emitter Saturation Voltage | V _{CE(SAT)} | — | — | -0.15 | V | I _C = -10 mA, I _B = -0.5 mA |
| | | — | — | -0.2 | V | I _C = -50mA, I _B = -5mA |
| | | — | — | -0.2 | V | I _C = -20mA, I _B = -1mA |
| | | — | — | -0.25 | V | I _C = -100mA, I _B = -10mA |
| | | — | — | -0.25 | V | I _C = -200mA, I _B = -10mA |
| | | — | — | -0.3 | V | I _C = -200mA, I _B = -20mA |
| Equivalent On-Resistance* | R _{CE(SAT)} | — | — | 1.5 | Ω | I _C = -200mA, I _B = -10mA |
| DC Current Gain | h _{FE} | 60 | 150 | — | — | V _{CE} = -5V, I _C = -20 mA |
| | | 60 | 215 | — | — | V _{CE} = -5V, I _C = -50 mA |
| | | 60 | 245 | — | — | V _{CE} = -5V, I _C = -100 mA |
| | | 60 | 250 | — | — | V _{CE} = -5V, I _C = -200 mA |
| Input On Voltage | V _{I(ON)} | -2.45 | -0.7 | — | V | V _O = -0.3V, I _C = -2 mA |
| Output Voltage (equivalent to V _{CE(SAT)} or V _{O(ON)}) | V _{OL} | — | -0.065 | -0.15 | V | V _{CC} = -5V, V _B = -2.5V, I _O /I _I = -50mA / -2.5mA |
| Input Current | I _i | — | -9 | -28 | mA | V _I = -5V |
| Base-Emitter Turn-on Voltage | V _{BE(ON)} | — | -1.13 | -1.3 | V | V _{CE} = -5V, I _C = 200mA |
| Base-Emitter Saturation Voltage | V _{BE(SAT)} | — | -3.2 | -3.6 | V | I _C = -50mA, I _B = -5mA |
| | | — | -4.6 | -5.5 | | I _C = -80mA, I _B = -8mA |
| Input Resistor (Base), +/- 30% | R ₂ | — | 0.47 | — | KΩ | — |
| Pull-up Resistor (Base to V _{CC} supply), +/- 30% | R ₁ | — | 10 | — | KΩ | — |
| Resistor Ratio (Input Resistor/Pull-up resistor) +/- 20% | R ₁ /R ₂ | — | 21 | — | — | — |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Transition Frequency (Gain Bandwidth Product) | f _T | — | 200 | — | MHz | V _{CE} = -10V, I _E = -5mA, f = 100MHz |
| Collector Capacitance, (C _{cb0} -Output Capacitance) | C _C | — | 20 | — | pF | V _{CB} = -10V, I _E = 0A, f = 1MHz |

* Pulse Test: Pulse width, tp < 300 μs, Duty Cycle, d <= 0.02

Electrical Characteristics: N-MOSFET with Gate Pull-Down Resistor (Q2)

@T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|----------------------|-----|------|-------|------|---|
| OFF CHARACTERISTICS (Note 4) | | | | | | |
| Drain-Source Breakdown Voltage, BV _{DSS} | V _{(BR)DSS} | 60 | — | — | V | V _{GS} = 0V, I _D = 10μA |
| Zero Gate Voltage Drain Current (Drain Leakage Current) | I _{DSS} | — | — | 1 | μA | V _{GS} = 0V, V _{DS} = 60V |
| Gate-Body Leakage Current, Forward | I _{GSSF} | — | — | 0.95 | mA | V _{GS} = 20V, V _{DS} = 0V |
| Gate-Body Leakage Current, Reverse | I _{GSSR} | — | — | -0.95 | mA | V _{GS} = -20V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 4) | | | | | | |
| Gate Source Threshold Voltage (Control Supply Voltage) | V _{GS(th)} | 1 | 1.9 | 2.2 | V | V _{DS} = V _{GS} , I _D = 0.25mA |
| Static Drain-Source On-State Voltage | V _{DS(on)} | — | 0.10 | 1.5 | V | V _{GS} = 5V, I _D = 50mA |
| | | — | 0.15 | 3.75 | | V _{GS} = 10V, I _D = 115mA |
| On-State Drain Current | I _{D(on)} | 500 | — | — | mA | V _{GS} = 10V, V _{DS} ≥ 2xV _{DS(on)} |
| Static Drain-Source On-Resistance | R _{DS(on)} | — | 1.6 | 3 | Ω | V _{GS} = 5V, I _D = 50mA |
| | | — | 1.4 | 2 | | V _{GS} = 10V, I _D = 500mA |
| Forward Transconductance | g _{FS} | 80 | 240 | — | mS | V _{DS} ≥ 2xV _{DS(on)} , I _D = 115 mA |
| | | 80 | 350 | — | | V _{DS} ≥ 2xV _{DS(on)} , I _D = 200 mA |
| Gate Pull-Down Resistor, +/- 30% | R3 | — | 37 | — | KΩ | — |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Input Capacitance | C _{iss} | — | — | 50 | pF | V _{DS} = -25V, V _{GS} = 0V, f = 1MHz |
| Output Capacitance | C _{oss} | — | — | 25 | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | — | 5 | pF | |
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Delay Time | t _{D(on)} | — | — | 20 | ns | V _{DD} = 30V, V _{GS} = 10V, I _D = 200mA, R _G = 25 Ohm, R _L = 150 Ohm |
| Turn-Off Delay Time | t _{D(off)} | — | — | 40 | ns | |
| SOURCE-DRAIN (BODY) DIODE CHARACTERISTICS AND MAXIMUM RATINGS | | | | | | |
| Drain-Source Diode Forward On-Voltage | V _{SD} | — | 0.90 | 1.5 | V | V _{GS} = 0V, I _S = 115 mA |
| Maximum Continuous Drain-Source Diode Forward Current (Reverse Drain Current) | I _S | — | — | 115 | mA | — |
| Maximum Pulsed Drain-Source Diode Forward Current | I _{SM} | — | — | 800 | mA | — |

Notes: 4. Short duration pulse test used to minimize self-heating effect.

Typical Characteristics

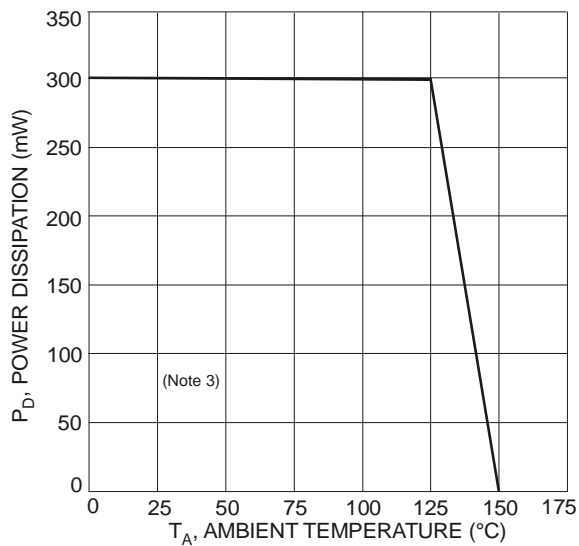


Fig. 3 Max Power Dissipation vs. Ambient Temperature (Total Device)

Typical Pre-Biased PNP Transistor (Q1) Characteristics

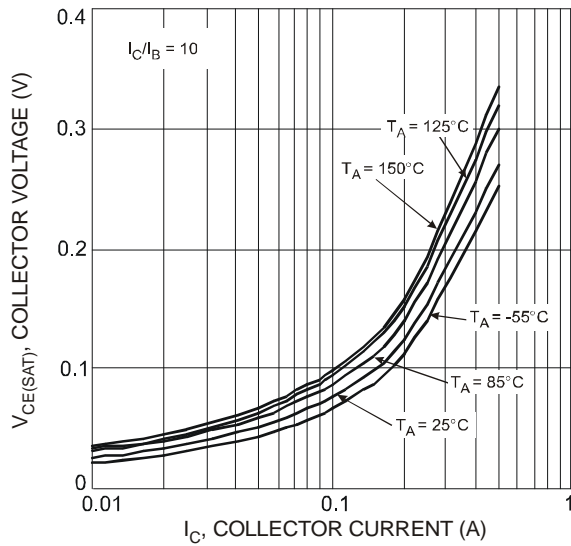


Fig. 4 $V_{CE(SAT)}$ vs. I_C

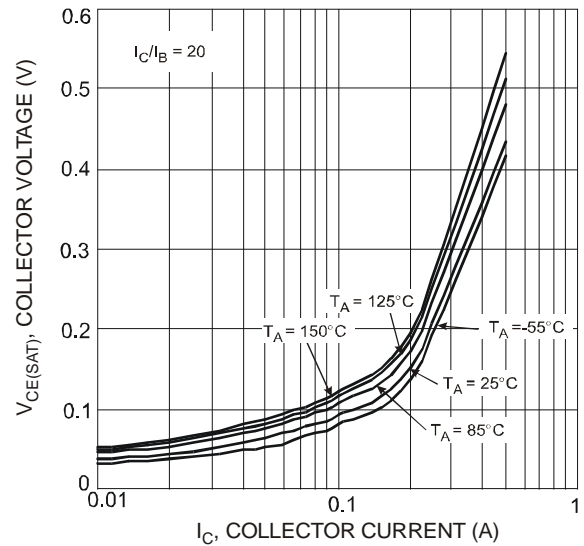


Fig. 5 $V_{CE(SAT)}$ vs. I_C

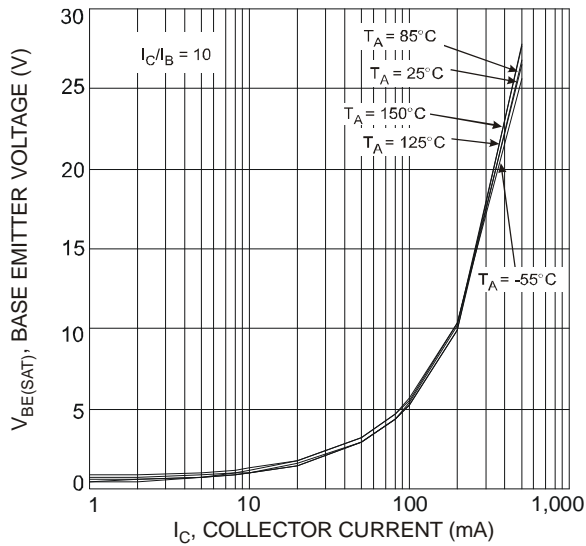


Fig. 6 $V_{BE(SAT)}$ vs. I_C

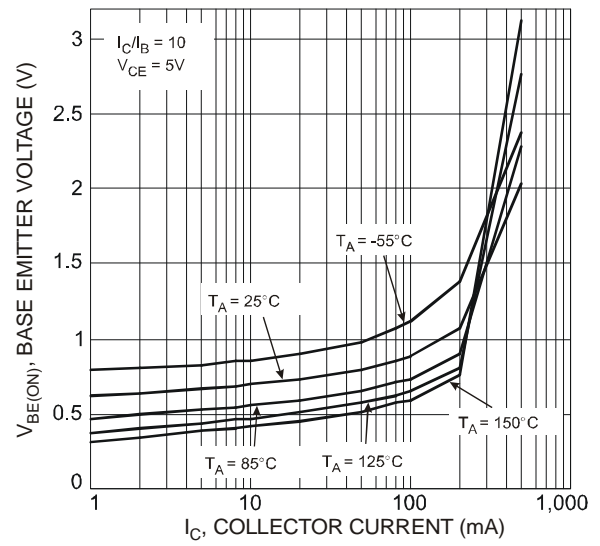


Fig. 7 $V_{BE(ON)}$ vs. I_C

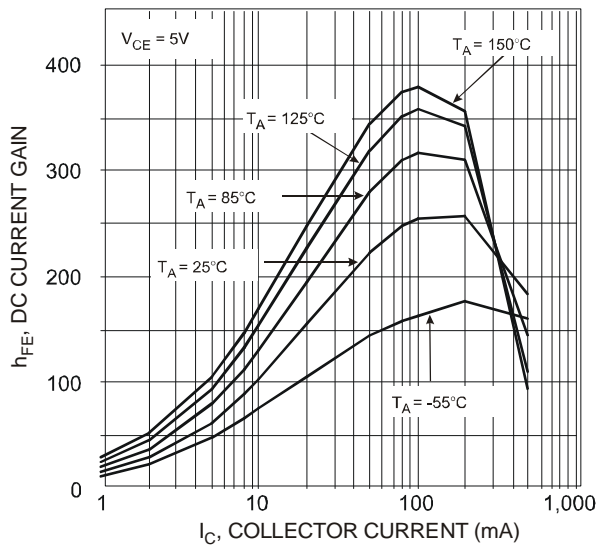


Fig. 8 h_{FE} vs. I_C

Typical N-Channel MOSFET (Q2) Characteristics

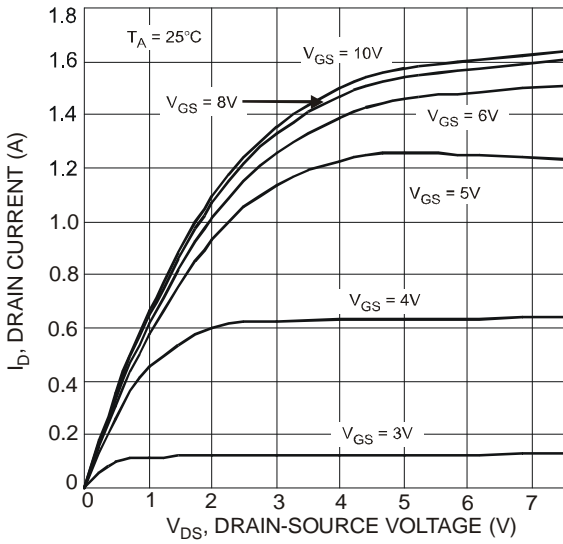


Fig. 9 Output Characteristics

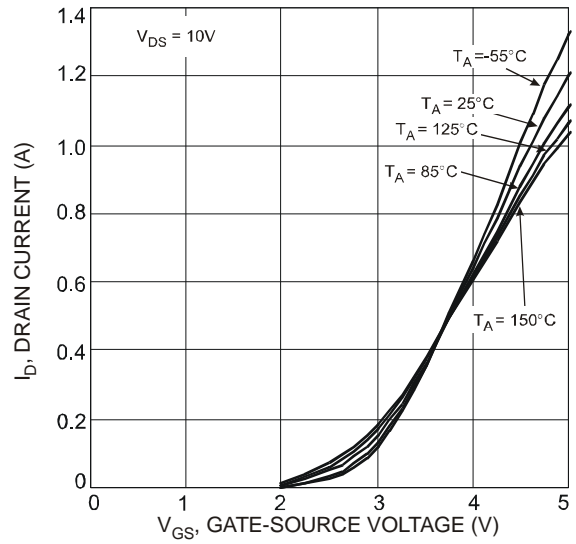


Fig. 10 Transfer Characteristics

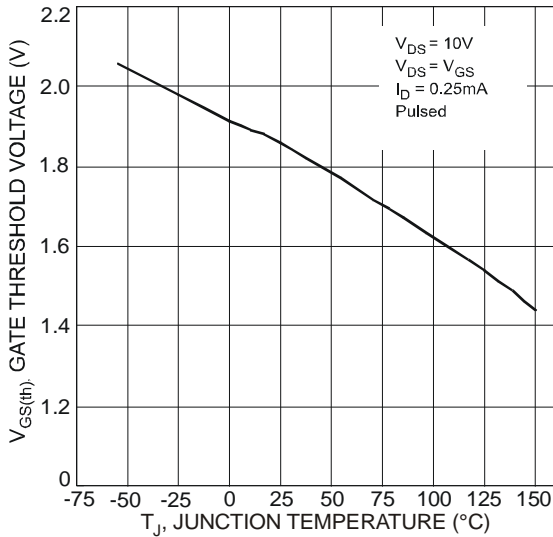


Fig. 11 Gate Threshold Voltage vs. Junction Temperature

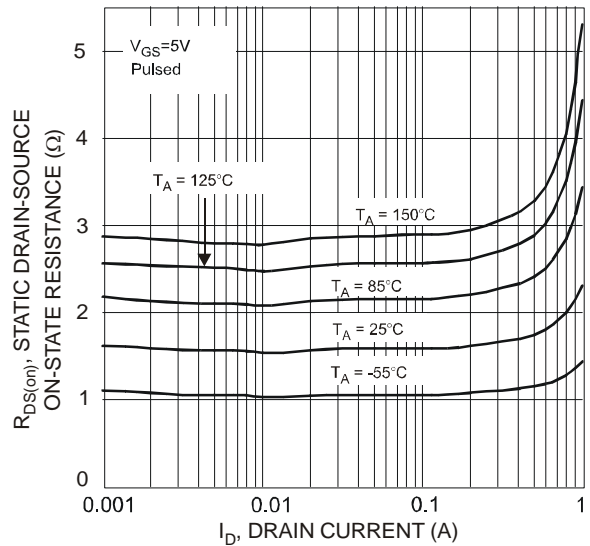


Fig. 12 Static Drain-Source On-Resistance vs. Drain Current

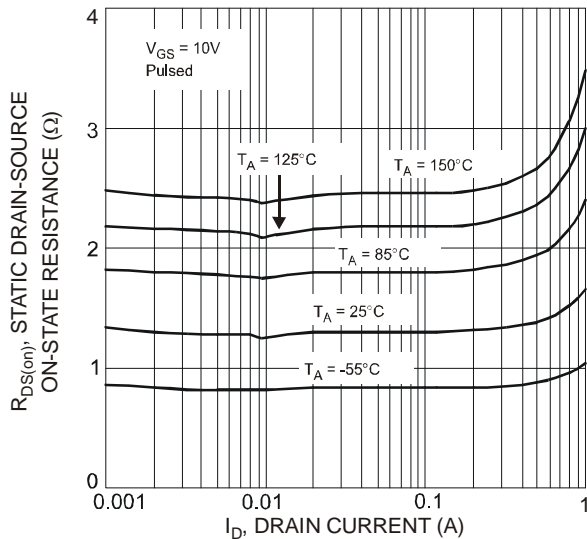


Fig. 13 Static Drain-Source On-Resistance vs. Drain Current

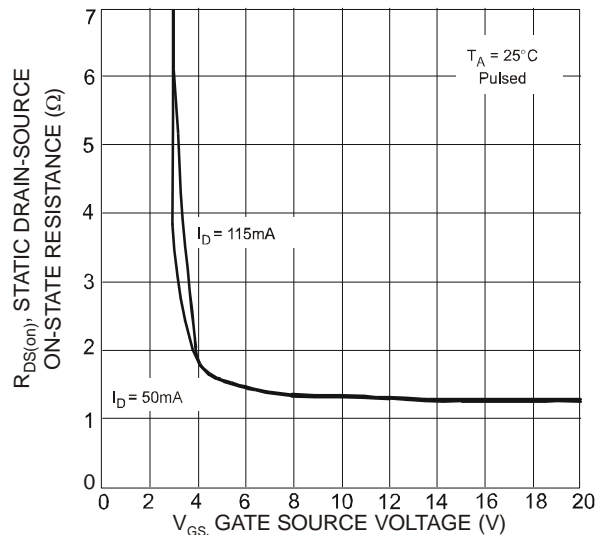


Fig. 14 Static Drain-Source On-Resistance vs. Gate-Source Voltage

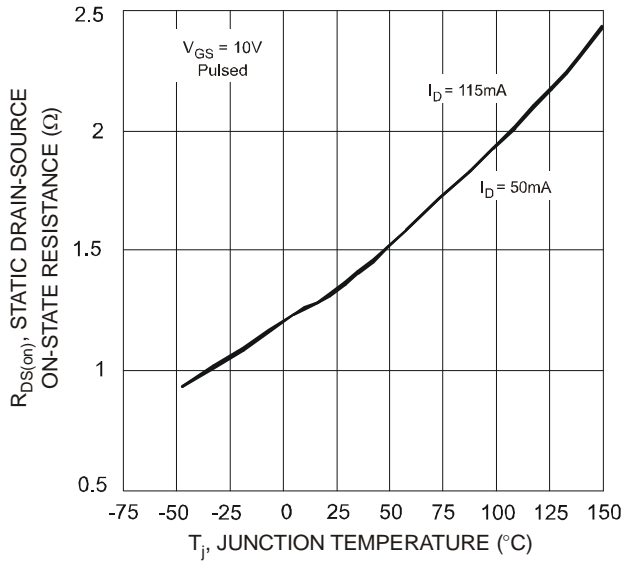


Fig. 15 Static Drain-Source On-State Resistance vs. Junction Temperature

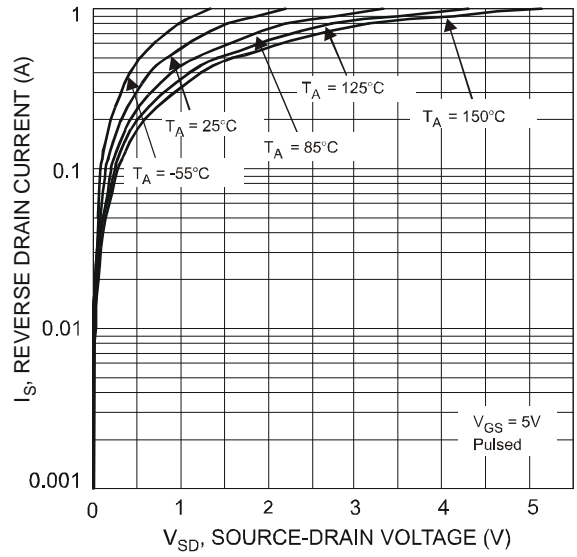


Fig. 16 Reverse Drain Current vs. Source-Drain Voltage

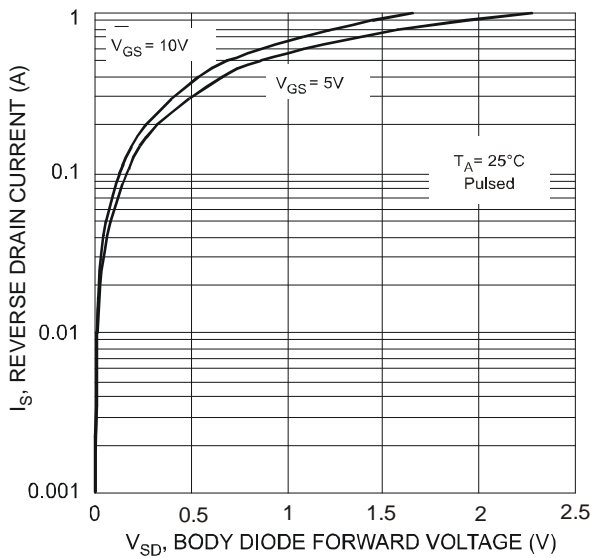


Fig. 17 Reverse Drain Current vs. Body Diode Forward Voltage

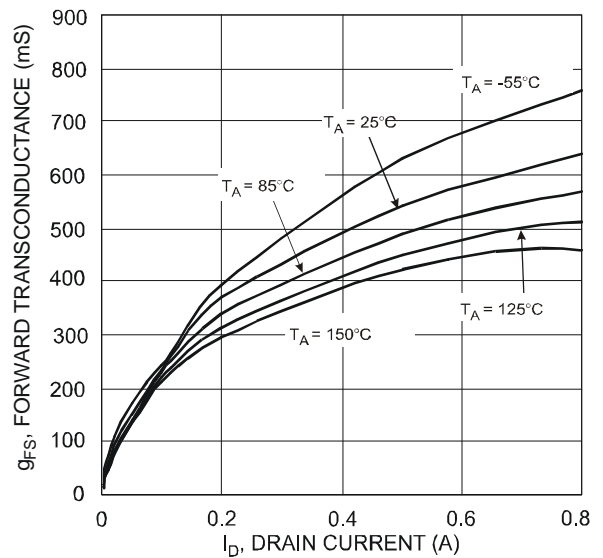


Fig. 18 Forward Transfer Conductance vs. Drain Current ($V_{DS} > I_D R_{DS(ON)}$)

Application Details

PNP Transistor (DDTB142JU) and N-MOSFET (DSNM6047) with gate pull-down resistor integrated as one in LMN200B02 can be used as a discrete entity for general purpose applications or as an integrated circuit to function as a Load Switch. When it is used as the latter as shown in Fig 19, various input voltage sources can be used as long as it does not exceed the maximum ratings of the device. These devices are designed to deliver continuous output load current up to a maximum of 200 mA. The MOSFET Switch draws no current, hence loading of control circuit is prevented. Care must be taken for higher levels of dissipation while designing for higher load conditions. These devices provide high power and also consume less space. The product mainly helps in optimizing power usage, thereby conserving battery life in a controlled load system like portable battery powered applications. (Please see Fig. 20 for one example of a typical application circuit used in conjunction with voltage regulator as a part of a power management system)

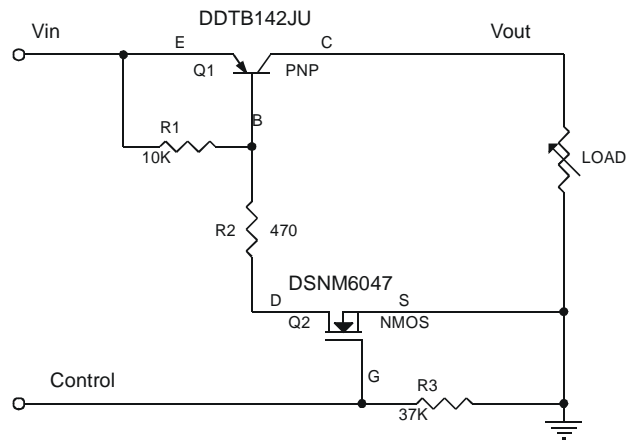


Fig. 19 Circuit Diagram

Typical Application Circuit

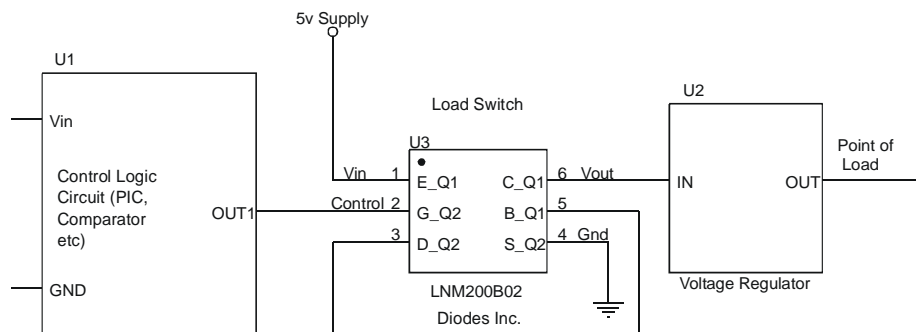


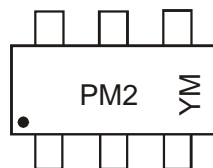
Fig. 20

Ordering Information (Note 5)

| Device | Packaging | Shipping |
|-------------|-----------|------------------|
| LMN200B02-7 | SOT-363 | 3000/Tape & Reel |

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



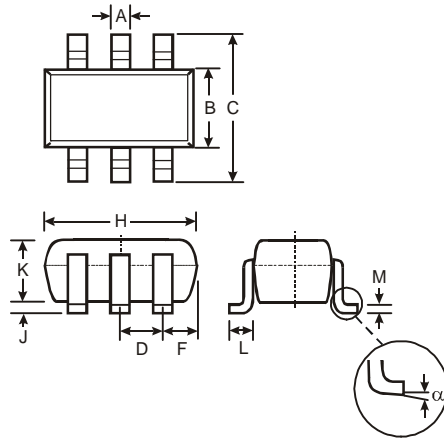
PM2 = Product Type Marking Code,
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

| Year | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 |
|------|------|------|------|------|------|------|------|------|------|------|
| Code | T | U | V | W | X | Y | Z | A | B | C |

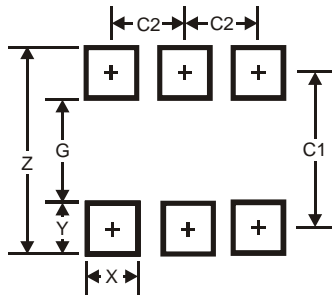
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Mechanical Details



| SOT-363 | | |
|----------------------|----------|------|
| Dim | Min | Max |
| A | 0.10 | 0.30 |
| B | 1.15 | 1.35 |
| C | 2.00 | 2.20 |
| D | 0.65 Typ | |
| F | 0.40 | 0.45 |
| H | 1.80 | 2.20 |
| J | 0 | 0.10 |
| K | 0.90 | 1.00 |
| L | 0.25 | 0.40 |
| M | 0.10 | 0.22 |
| α | 0° | 8° |
| All Dimensions in mm | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.5 |
| G | 1.3 |
| X | 0.42 |
| Y | 0.6 |
| C1 | 1.9 |
| C2 | 0.65 |

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